

National Nanotechnology Coordinated Infrastructure





#### THERMAL CONDUCTIVITY MEASUREMENT OF POLYMER FIBERS USING THE FOUR-PROBE METHOD

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## INTRODUCTION

Electronic components rely on the passage of current to operate. Since current flow through a resistance is accompanied by **heat generation**, these components become potential sites for excessive heating which can cause them to fail. It's very desirable to develop devices made from materials that efficiently **control heat flow** 

to protect heat sensitive components.



top or Desktop Overheating Service - Computer Fan Repair. (n.d.). Retrieved from http://icomputerdenver.com/computer-fan-overheating-and-power-down-problems/





## **INTRODUCTION: THERMAL CONDUCTIVITY**

How do we know how much heat travels within a material?

$$q_x\hat{\imath} + q_y\hat{\jmath} + q_z\hat{k} = -\mathbf{k}\left(\frac{\partial T}{\partial x}\hat{\imath} + \frac{\partial T}{\partial y}\hat{\jmath} + \frac{\partial T}{\partial z}\hat{k}\right)$$
$$\vec{q} = -\mathbf{k}\vec{\nabla}T$$



Thermal conductivity measures the ability of a material to conduct heat.

Heat transfer occurs at a higher rate across materials of high thermal conductivity than those of low thermal conductivity.





## **INTRODUCTION: THERMAL RECTIFICATION**

Can you imagine a material that's able to control the heat flux along a specific axis, having a higher thermal conductivity value in one direction and at the same time insulate in the opposite direction?

Thermal rectifiers exhibit these properties. **Thermal rectification** is a phenomenon in which heat flow along a specific axis is preferred in one direction than in the other.





## **INTRODUCTION: OBJECTIVES**

#### Main

Investigate if a polymer fiber synthesized by Prof. Wudl's group exhibits

thermal rectification properties.

#### **Specific**

• Fabricate a thermal conductivity measuring device with four suspended heater lines.

• Measure the thermal conductivity a polymer fiber synthesized by Prof. Wudl's group.



#### FABRICATION PROCESS OF OUR THERMAL CONDUCTIVITY MEASURING DEVICE



## FABRICATION PROCESS: DEPOSITION STEPS



Silicon wafer



400nm  $Si_3N_4$ 

Tool: Nitride Furnace

10nm Titanium and 60nm Platinum

**Tool:** Denton Explorer Ebeam Evaporator



## FABRICATION PROCESS: PHOTOLITHOGRAPHY





2 μm negative photoresist NR-1500 PY **Tool:** SCS G3P8 Spin Coater 1 UV light shines on the sample **Tool:** Karl Suss MA-6 Mask Aligner

Develop photoresist with RD-6



#### FABRICATION PROCESS: ICP ETCHING



Platinum is etched

**Tool:** Plasma Therm ICP

Silicon Nitride is etched Photoresist is removed with acetone.



## FABRICATION PROCESS: SECOND PHOTOLITHOGRAPHY



2 μm positive photoresist SC 1813 **Tool:** SCS G3P8 Spin Coater 1 Mask and wafer alignment UV light shines on the sample **Tool:** Karl Suss MA-6 Mask Aligner

UV



Develop photoresist with MF-319



### FABRICATION PROCESS: XENON DIFLUORIDE ETCH



Silicon is etched

Tool: Xactix Xenon Difluoride Etcher

Remaining photoresist is removed with Acetone.



# RESULTS



### **PROBLEMS DURING THE FABRICATION PROCESS**



Some of the **problems** that we faced during the fabrication process were:

- Features being washed away with the developer
- Broken and bent heater lines.

After evaluating the **main parameters** involved in the process, we found the solution to these problems as you will notice in the following slides

Bent and broken heater lines



## **RESULTS: TITANIUM AND PLATINUM DEPOSITION**



Denton Explorer E-beam Evaporator



10nm Titanium and 60nm Platinum



## **RESULTS: FIRST PHOTOLITHOGRAPHY**

After negative photoresist is spin coated into the wafer we expose it to UV light using a mask to create features in the wafer. Negative photoresist hardens when exposed to UV light, the rest will get washed away with the developer.





## **RESULTS: ICP ETCHING**

Platinum and silicon nitride are etched







## **RESULTS: SECOND PHOTOLITHOGRAPHY**

After positive photoresist is spin coated into the wafer we expose it to UV light using a mask to create features in the heater lines. Positive photoresist softens when exposed to UV light and will get washed away with the developer.







## **RESULTS: XENON DIFLUORIDE ETCHING**

One micrometer of silicon is etched. The result is 4 suspended heater lines.



Picture taken by Aravindh Rajan



## **RESULTS: FOUR-PROBE THERMAL MEASURING DEVICE**



We succeeded in fabricating a thermal conductivity measurement device.



## **CONCLUSIONS AND RECOMMENDATIONS**



## **CONCLUSIONS AND RECOMMENDATIONS**

Our four-probe thermal conductivity measuring device was fabricated in a reproducible way and with the desired specifications.

The process takes a long time to complete and modifications are suggested to save time and speed up the production.

One of these is to make two separate masks with different features on each. By doing this, more features can be obtained from one wafer.





#### FUTURE WORK



We apply a known current (I) through 2, to heat the polymer. Through 1 we send a small current, we measure the voltage (V) drop and using Ohm's Law we calculate the Resistance (R).



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## QUESTIONS?